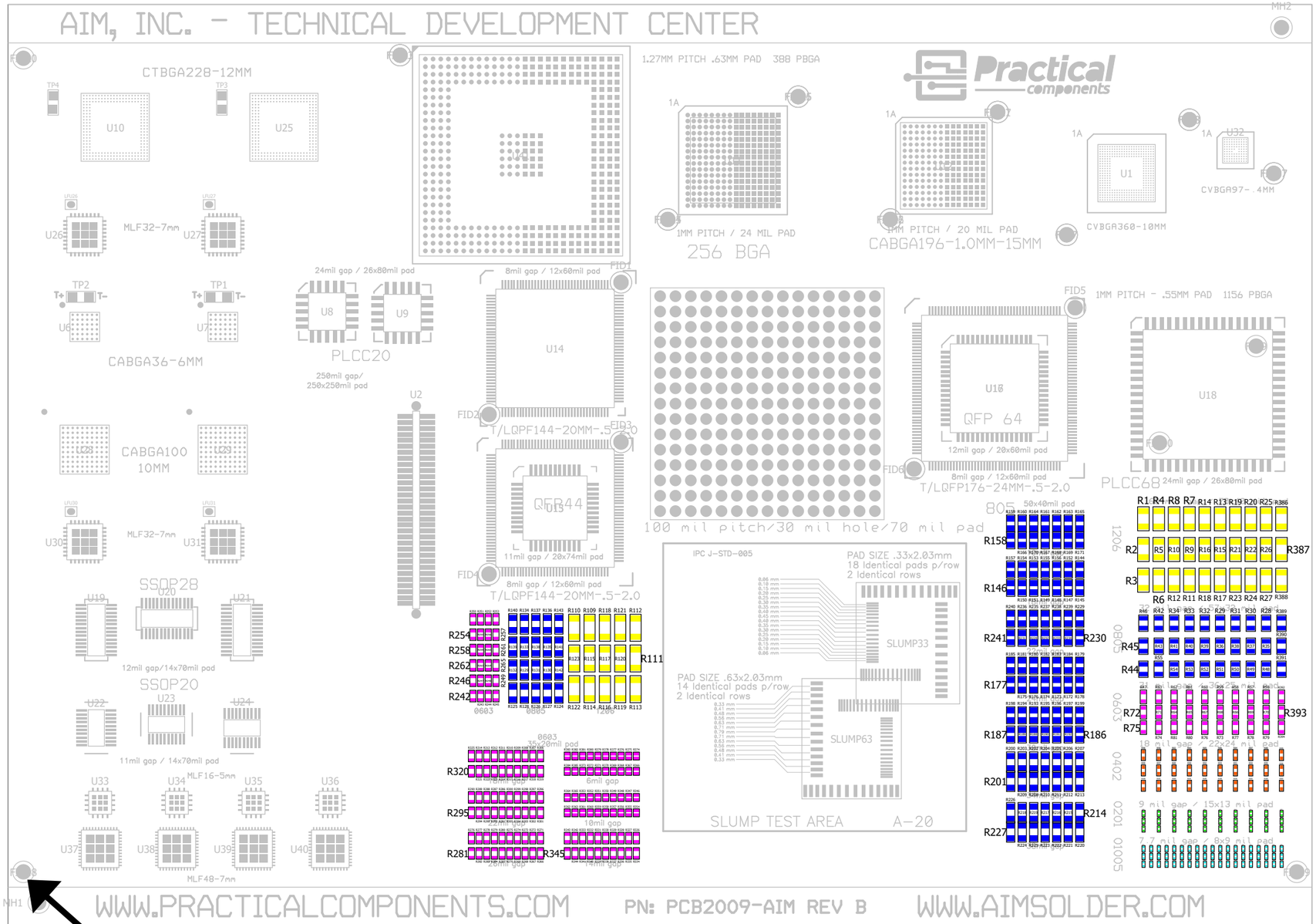


Fiducial is 0,0

Color	Part Number	Reference	Qty
	0201	R398-R427	30
	1005	R428-R484	57
	0402	R82-R108, R395-R397	30
	0603	R47, R56-R81, R242-R385, R392-R394	174
	0805	R28-R46, R48-R55, R124-R241, R389-R391	148
	1206	R1-R27, R109-R123, R386-R388	45

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SMT Placement

Operation	Assembly - Rev
	PCB2009-AIM - B
	PC2009 AIM Solder Print Test Board

Customer

Practical Components

Comments

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Standards

Page	1
Of	5

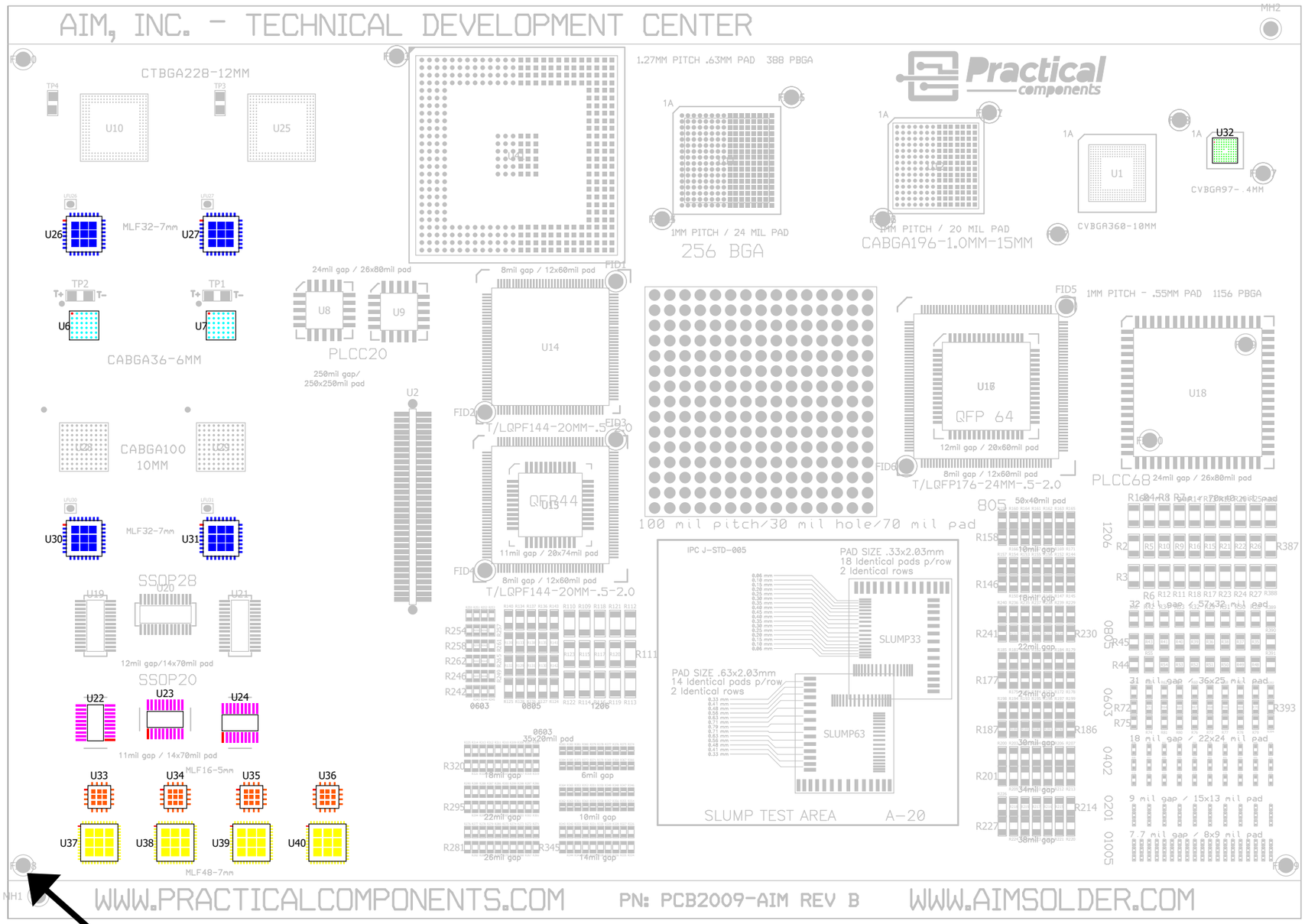
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Solder practice test vehicle PCB boards and kits are for machine setup, evaluation, qualification, workflow analysis, prototyping, testing, solder profiling.

Common pad sizes were incorporated into the layout including 1206, 0805 and 0603 rectangular pads for discrete components. These pads have varying distance between them so the user can determine solder beading of paste. Four 250 x 250mil pads are available to be utilized with various aperture styles in order to allow for wetting tests. There are also several fine pitch QFP pads designed to check for the propensity of any given product to cause bridging and to confirm the existence of torn prints, peaking (dog ears), or bridging.

Kit available with Tin/Lead and Pb-free components.
Board material is IS-410.
Standard finish: ImAg.
Board size: 8.5" x 6"

Practical components



Fiducial is 0,0

Color	Part Number	Reference	Qty
	CVBGA97	U32	1
	CABGA36	U6-U7	2
	MLF16	U33-U36	4
	SSOP20	U22-U24	3
	MLF32	U26-U27, U30-U31	4
	MLF48	U37-U40	4

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SMT Placement

Customer

Practical Components

Operation

Assembly - Rev

PCB2009-AIM - B

PC2009 AIM Solder Print Test Board

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Standards

Page	2
Of	5

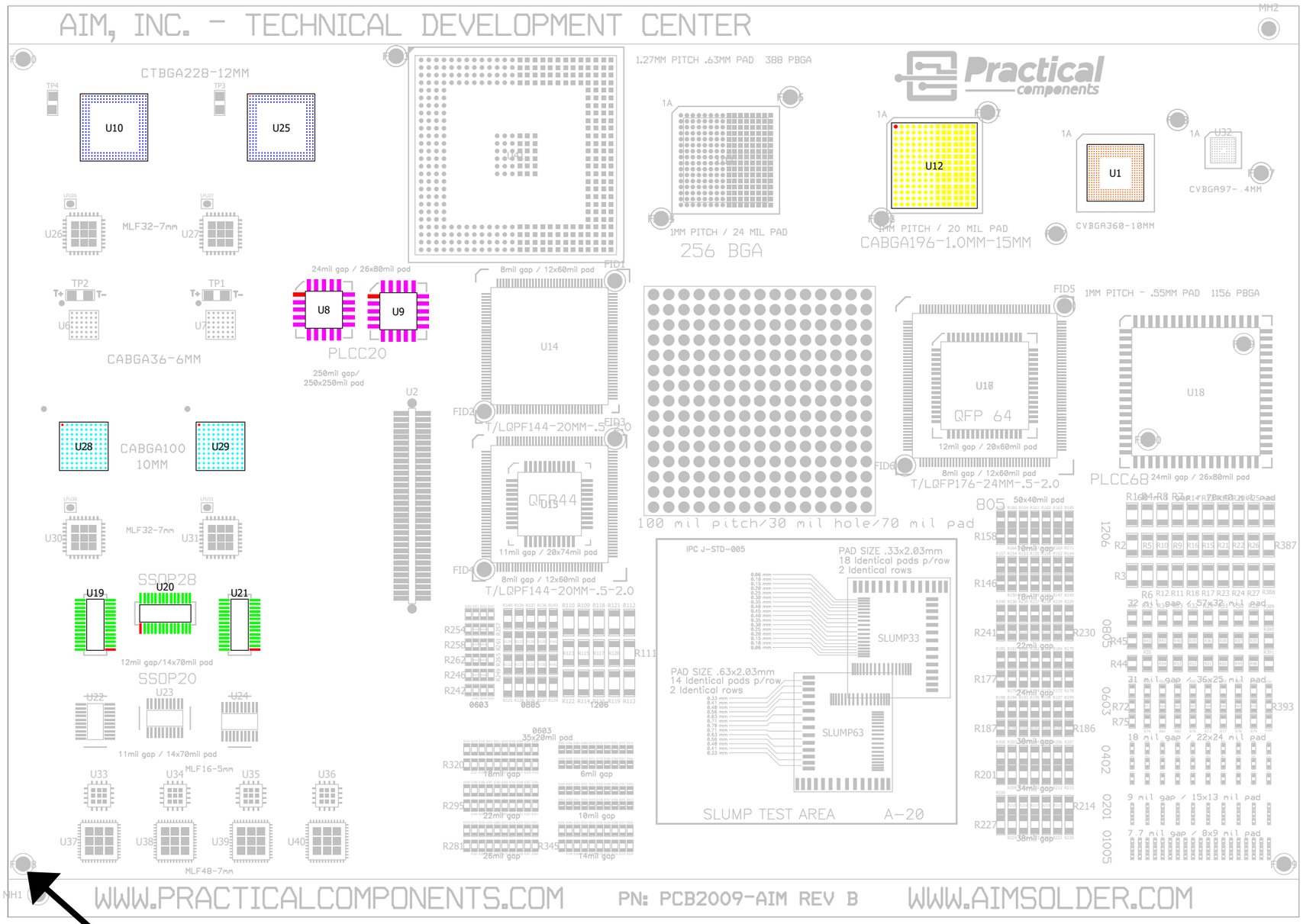
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Color	Part Number	Reference	Qty
	SSOP28	U19-U21	3
	CABGA100	U28-U29	2
	CVBGA360	U1	1
	PLCC20	U8-U9	2
	CTBGA228	U10, U25	2
	PBGA196-1.0-15mm	U12	1

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Operation	Assembly - Rev	Standards
SMT Placement	PCB2009-AIM - B	
	PC2009 AIM Solder Print Test Board	
Customer	**Comments**	**Page** 3
Practical Components	Going paperless? Aegis can support your entire factory with a singular authoring environment using ECAD, 2D CAD, and 3D CAD for all of your operational processes.	**Of** 5

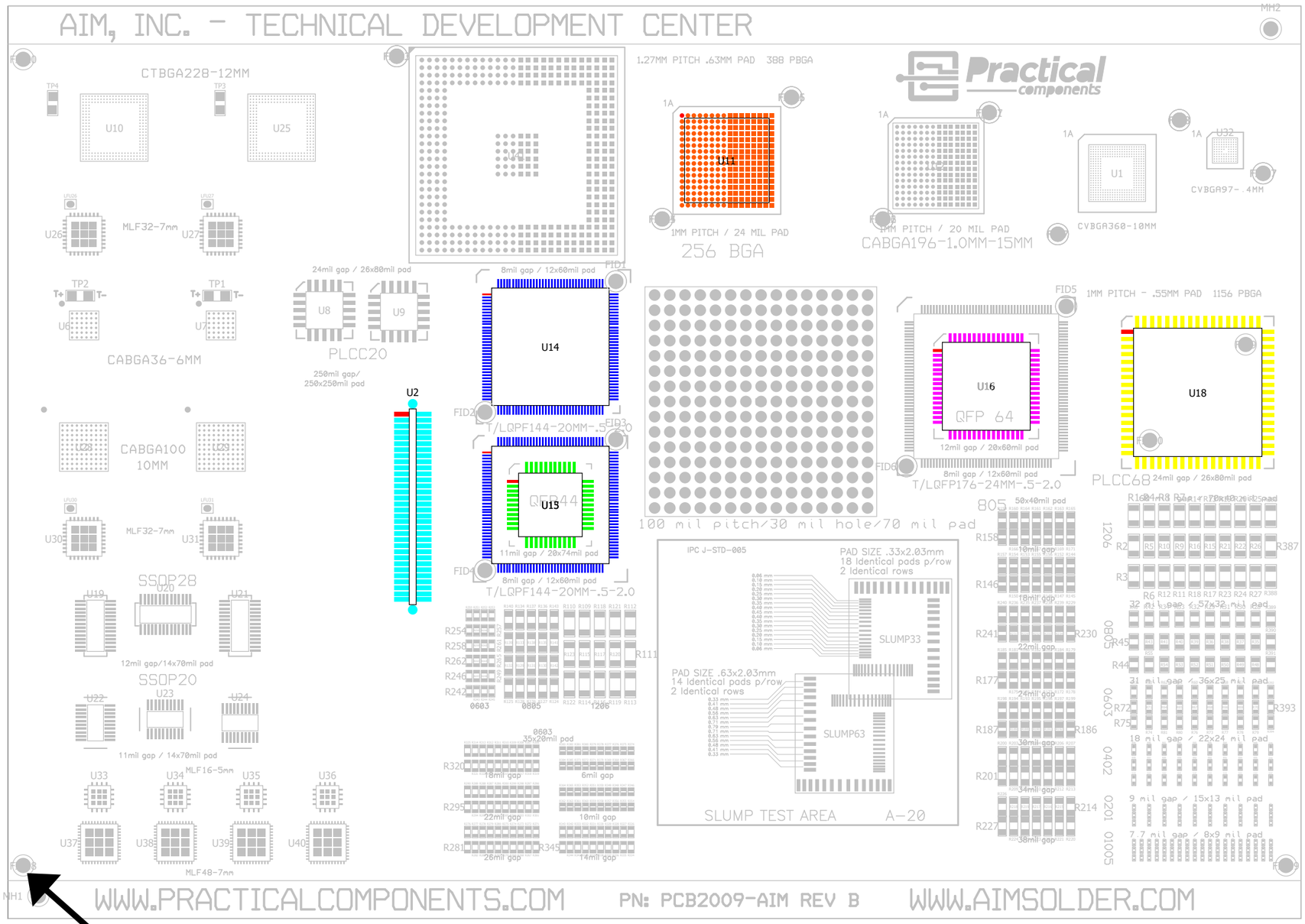
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Color	Part Number	Reference	Qty
	QFP44-10mm-.8-3.2/3.9	U15	1
	CONN-SMT-140-LEAD	U2	1
	PBGA256-1mm-17X17	U11	1
	QFP64-14mm-.8-3.2	U16	1
	TQFP144-20mm-.5-2.0	U13-U14	2
	PLCC68	U18	1

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Operation	Assembly - Rev	Standards
SMT Placement	PCB2009-AIM - B	
	PC2009 AIM Solder Print Test Board	
Customer	**Comments**	**Page** 4
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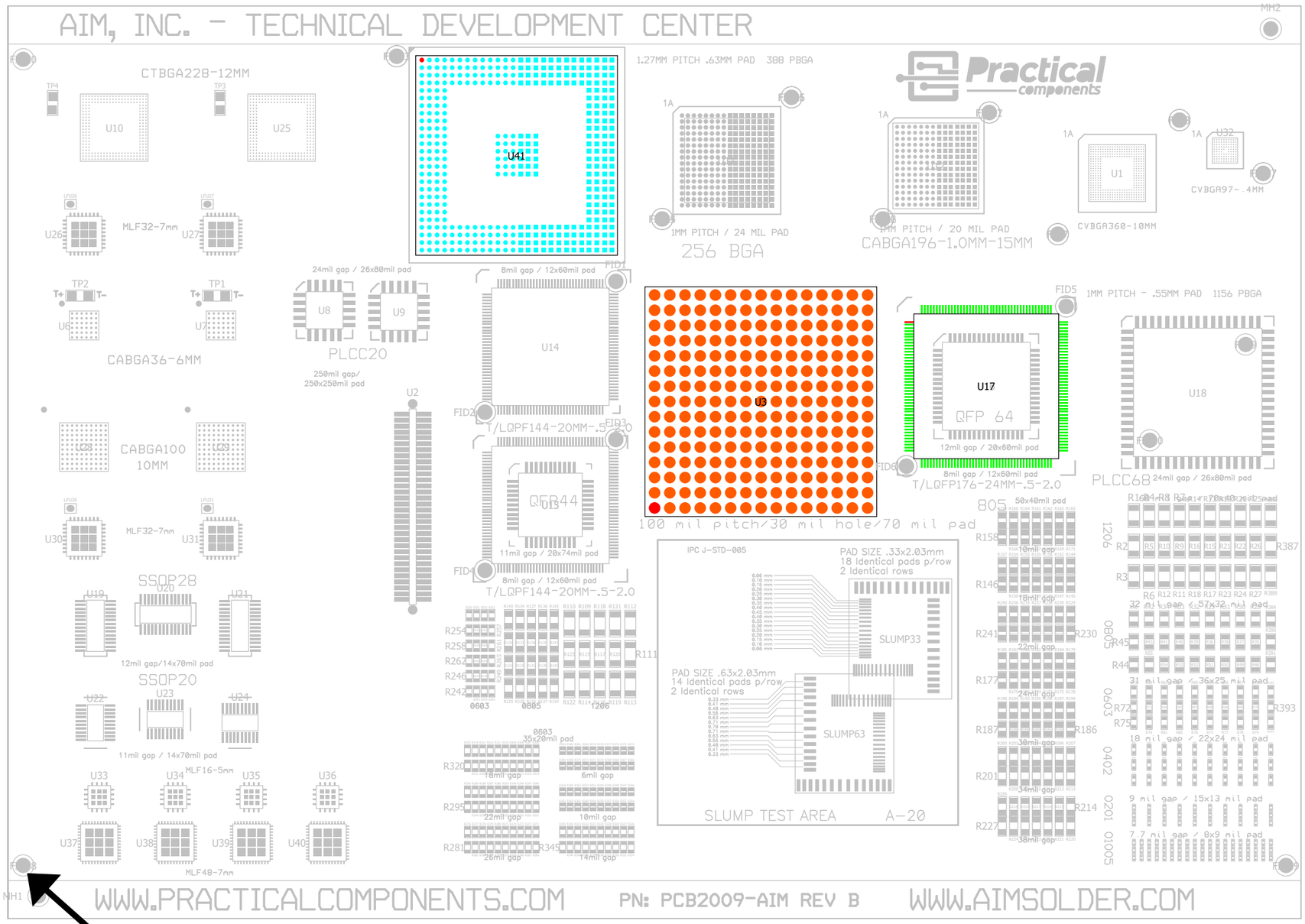
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Color	Part Number	Reference	Qty
	LQFP176-24mm-.5-2.0	U17	1
	BGA388	U41	1
	BGA225	U3	1

	Operation	Assembly - Rev	Standards
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		PC2009 AIM Solder Print Test Board	
	Customer	**Comments**	**Page** 5
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